

## Claims

1. An optoelectronic component (1) comprising a housing body (2) and at least one semiconductor chip (8) disposed thereon, said housing body having a base part (13) comprising a connector body (16), on which a connecting conductor material (6, 7) is disposed, and having a reflector part (14) comprising a reflector body (23), on which a reflector material (9) is disposed, characterized in that  
said connector body and said reflector body are preformed separately from each other and said reflector body is disposed on said connector body in the form of a reflector top.
2. The optoelectronic component as in claim 1,  
characterized in that  
said base part and said reflector part are preformed separately from each other.
3. The optoelectronic component as in claim 1 or 2,  
characterized in that  
said housing body contains a ceramic.
4. The optoelectronic component as in one of the preceding claims,  
characterized in that  
said housing body contains aluminum nitride or aluminum oxide.
5. The optoelectronic component as in one of the preceding claims,  
characterized in that  
said connecting conductor material is different from said reflector material.
6. The optoelectronic component as in one of the preceding claims,  
characterized in that  
said connecting conductor material contains a metal.

7. The optoelectronic component as in one of the preceding claims, characterized in that  
said reflector material contains a metal.
8. The optoelectronic component as in one of the preceding claims, characterized in that  
said connecting conductor material contains Au and said reflector material Ag.
9. The optoelectronic component as in one of the preceding claims, characterized in that  
said housing body has a cavity (3) in which said semiconductor chip is disposed.
10. The optoelectronic component as in one of the preceding claims, characterized in that  
said reflector body is provided with a recess (30), said recess is part of the cavity of the housing body and said reflector material is disposed on a wall (5) of said recess.
11. The optoelectronic component as in one of the preceding claims, characterized in that  
said reflector material is electrically insulated from said connecting conductor material.
12. The optoelectronic component as in one of the preceding claims, an insulation part (15) is disposed between said base part and said reflector part.
13. The optoelectronic component as in claim 12, characterized in that  
said insulation part is preformed separately from said base part and said reflector part.

14. The optoelectronic component as in one of the preceding claims, characterized in that disposed on said base part, particularly after said reflector part, is an adhesion promoting part (24) provided with a recess that is part of the cavity of said housing body.

15. The optoelectronic component as in claim 14, characterized in that disposed in the cavity of said housing body is an envelope (10) that at least partially envelops said semiconductor chip.

16. The optoelectronic component as in one of the preceding claims, characterized in that said envelope is arranged at said adhesion promoting part and said envelope adheres better to said adhesion promoting part than it does to said reflector material.

17. The optoelectronic component as in one of the preceding claims, characterized in that said base part includes a heat sink (22).

18. The optoelectronic component as in claim 17, characterized in that said heat sink is electrically insulated from said semiconductor chip.